

## Photo DMOS-FET Relay

### Description

The **LT915-1** is a miniature 1-Form A solid state relay in a 6 pin SMD package that employs optically coupled MOSFET technology to provide 3750V of input to output isolation. The optically coupled input is controlled by a highly efficient GaAlAs infrared LED and MOS FETs on the output side.

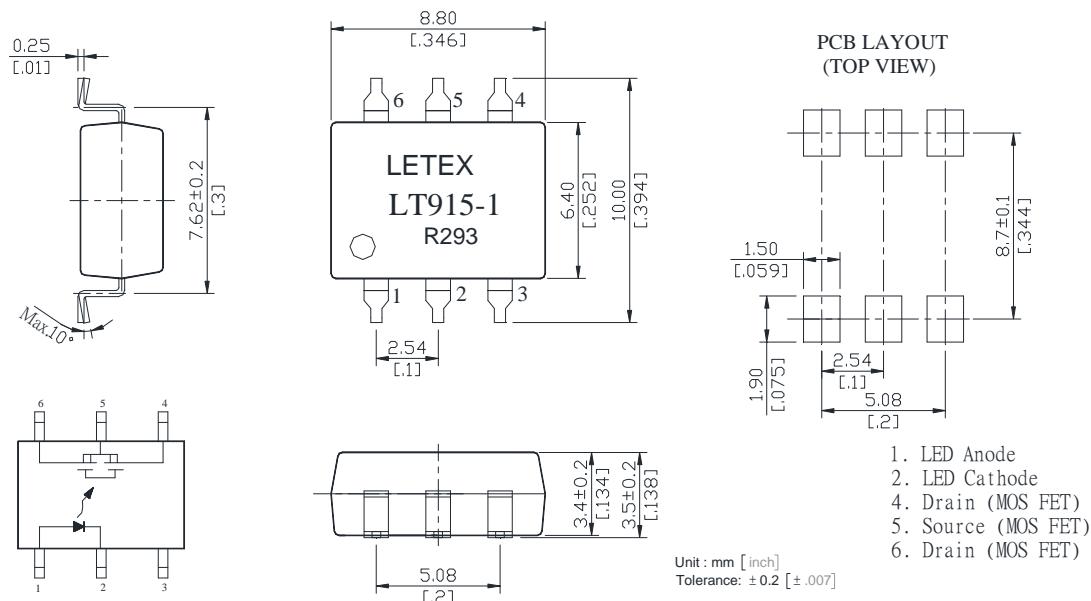
### Features

- Low driver power requirements (TTL/CMOS Compatible)
- High reliability
- Arc-Free with no snubbing circuits
- 3750Vrms Input/Output isolation
- Tape & Reel version available

### Applications

- Telecommunications (PC, Electronic notepad)
- Measuring and Testing equipment
- Industrial control
- Security equipments
- High speed inspection machine

### Outline Dimensions



## Photo DMOS-FET Relay Specifications

**Part Name: LT915-1**

(Load voltage: 60V / Load current: 2.5A)

Absolute Maximum Ratings (Ambient Temperature: 25°C)

| Item                      |                          | Symbol            | Value       | Units            | Note                |
|---------------------------|--------------------------|-------------------|-------------|------------------|---------------------|
| Input                     | Continuous LED Current   | I <sub>F</sub>    | 50          | mA               |                     |
|                           | Peak LED Current         | I <sub>FP</sub>   | 1000        | mA               | f=100Hz,<br>duty=1% |
|                           | LED Reverse Voltage      | V <sub>R</sub>    | 5           | V                |                     |
|                           | Input Power Dissipation  | P <sub>In</sub>   | 75          | mW               |                     |
| Output                    | Load Voltage             | V <sub>L</sub>    | 60          | V(AC peak or DC) |                     |
|                           | Load Current             | I <sub>L</sub>    | 2.5         | A                |                     |
|                           | Peak Load Current        | I <sub>Peak</sub> | 4.0         | A                | 100ms(1 pulse)      |
|                           | Output Power Dissipation | P <sub>out</sub>  | 450         | mW               |                     |
| Total Power Dissipation   |                          | P <sub>T</sub>    | 500         | mW               |                     |
| I/O Breakdown Voltage     |                          | V <sub>I/O</sub>  | 3750        | Vrms             | RH=60%, 1min        |
| Operating Temperature     |                          | T <sub>opr</sub>  | -40 to +85  | °C               |                     |
| Storage Temperature       |                          | T <sub>stg</sub>  | -40 to +100 | °C               |                     |
| Pin Soldering Temperature |                          | T <sub>sol</sub>  | 260         | °C               | 10 sec max.         |

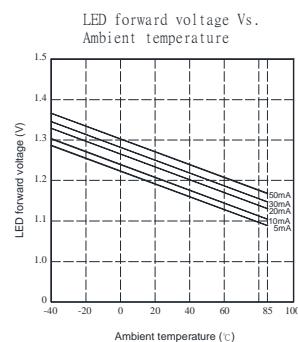
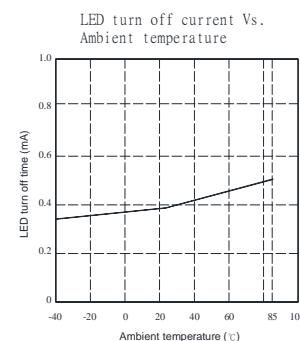
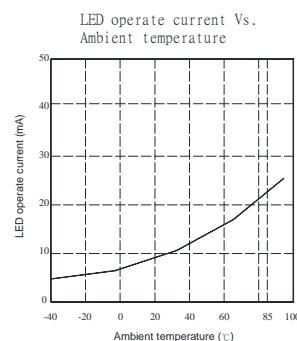
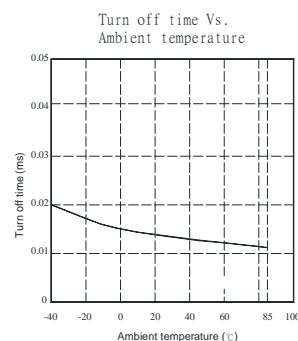
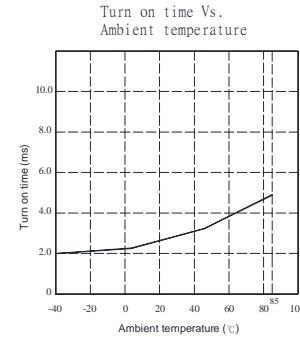
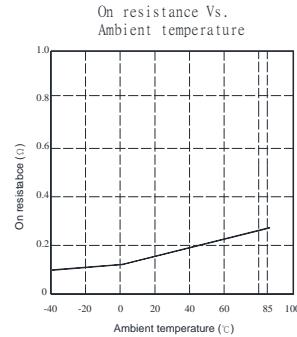
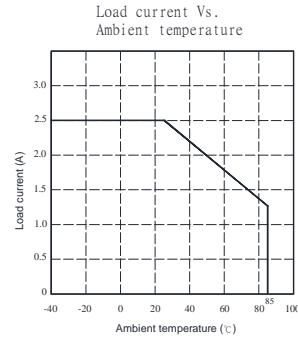
Electrical Specifications (Ambient Temperature: 25°C)

| Item         |                           | Symbol             | MIN.             | TYP. | MAX. | Units | Conditions  |
|--------------|---------------------------|--------------------|------------------|------|------|-------|---|
| Input        | LED Forward Voltage       | V <sub>F</sub>     |                  | 1.2  | 1.5  | V     | I <sub>F</sub> =10mA  |
|              | Operation LED Current     | I <sub>F on</sub>  | 5                | 10   | 25   | mA    |   |
|              | Recovery LED Current      | I <sub>F off</sub> |                  | 0.35 | 0.5  | mA    |   |
|              | Recovery LED Voltage      | V <sub>F off</sub> | 0.7              |      |      | V     |   |
| Output       | On-Resistance             | R <sub>on</sub>    |                  | 0.1  | 0.2  | Ω     | I <sub>F</sub> =5mA, I <sub>L</sub> =100mA,<br>Time to flow is within<br>1 sec. |
|              | Off-State Leakage Current | I <sub>Leak</sub>  |                  |      | 1    | uA    | V <sub>L</sub> =Rating  |
|              | Output Capacitance        | C <sub>out</sub>   |                  |      | -    | pF    | V <sub>L</sub> =0, f=1MHz   |
| Transmission | Turn-On Time              | T <sub>on</sub>    |                  |      | 5.0  | ms    | I <sub>F</sub> =5mA, I <sub>L</sub> =100mA,                                     |
|              | Turn-Off Time             | T <sub>off</sub>   |                  |      | 2.0  | ms    |   |
| Coupled      | I/O Isolation Resistance  | R <sub>I/O</sub>   | 10 <sup>10</sup> |      |      | Ω     | DC500V  |
|              | I/O Capacitance           | C <sub>I/O</sub>   |                  | 0.8  | 1.5  | pF    | f=1MHz  |

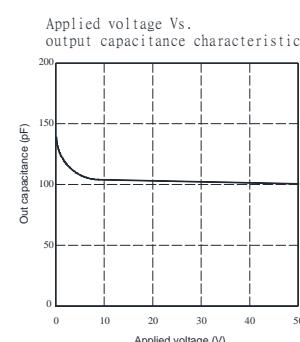
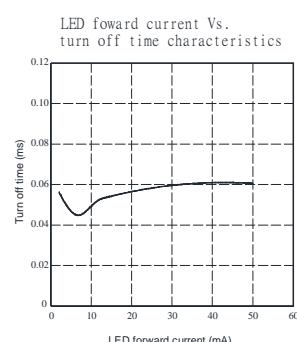
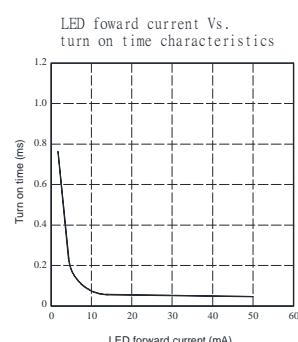
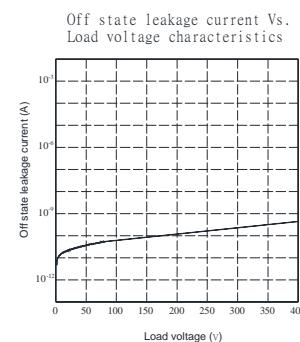
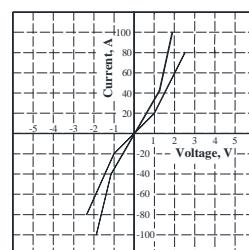


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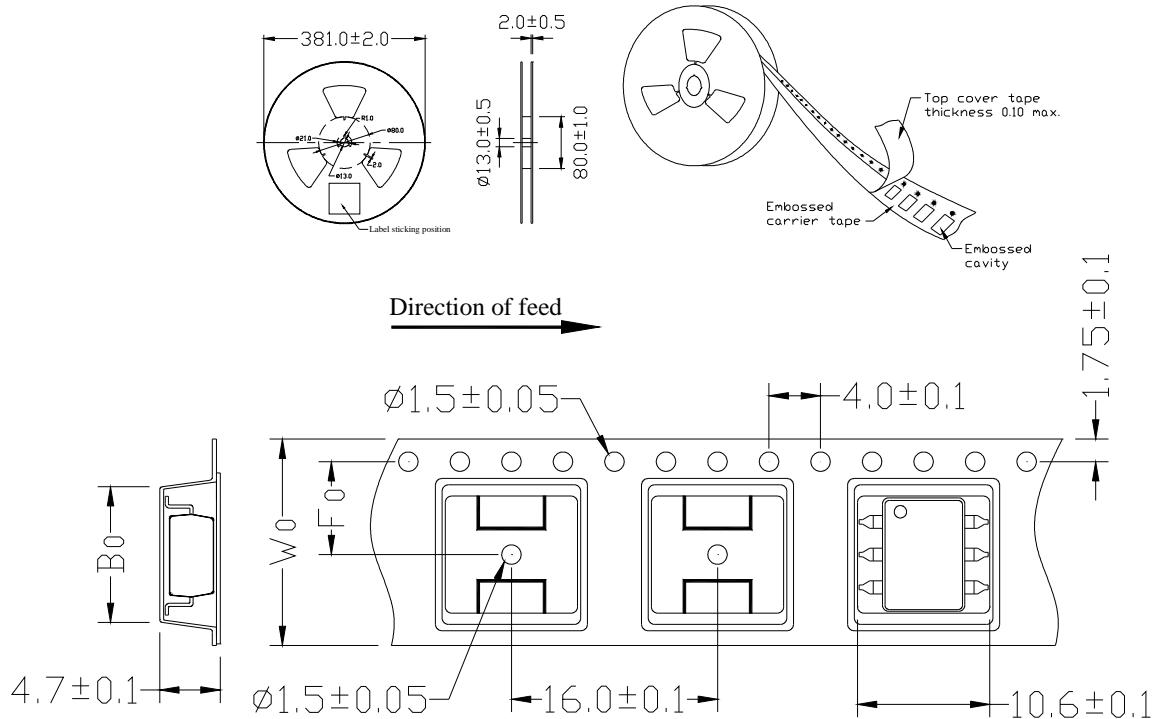
## Reference Data



Voltage Vs. current characteristics  
of output at MOS portion



## Taping Specifications for Surface Mount Devices

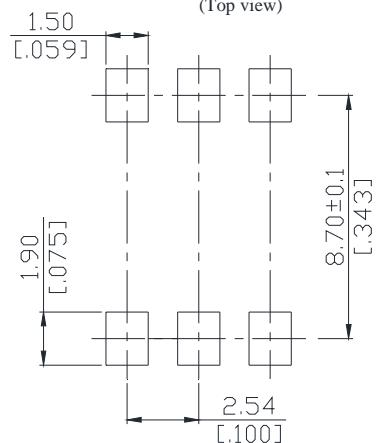


Unit: mm

| TYPE | B0±0.1 | F0±0.1 | W0±0.1 | 13" REEL/PCS |
|------|--------|--------|--------|--------------|
| 4P   | 5.3    | 7.5    | 16     | 1000         |
| 6P   | 9.4    | 7.5    | 16     | 1000         |
| 8P   | 10.3   | 11.5   | 24     | 1000         |

### Recommended Mounting Pad

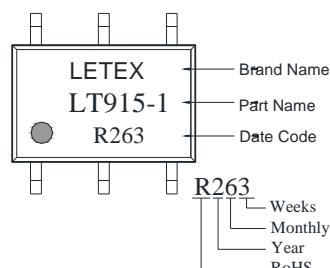
(Top view)



Unit : mm [inch]  
Tolerance : ±0.1

### Marking

(Each photo MOS Relay shall be marked with the following information)



- Note:
1. There shall be leader of 230 mm minimum which may consist of carrier and or cover tape follower by a minimum of 160 mm of carrier tape sealed with cover tape.
  2. There shall be a minimum of 160 mm of empty component pockets sealed with cover tape.
  3. Devices are pockets in accordance with EIA standard EIA-481-A and specifications given above.

